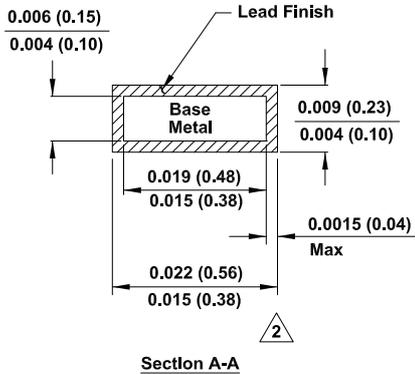
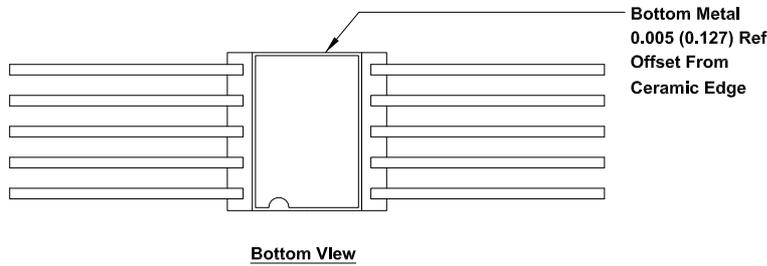
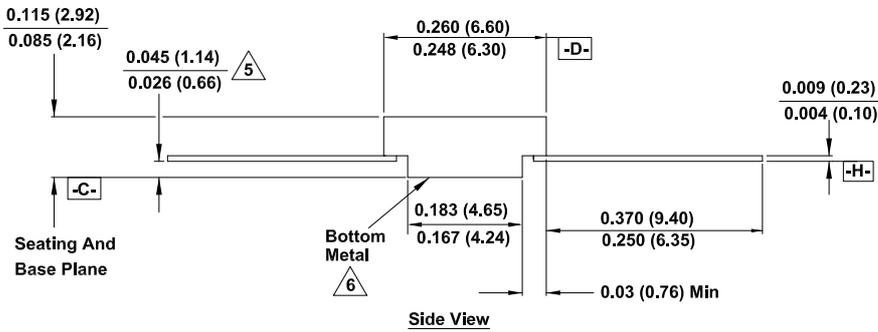
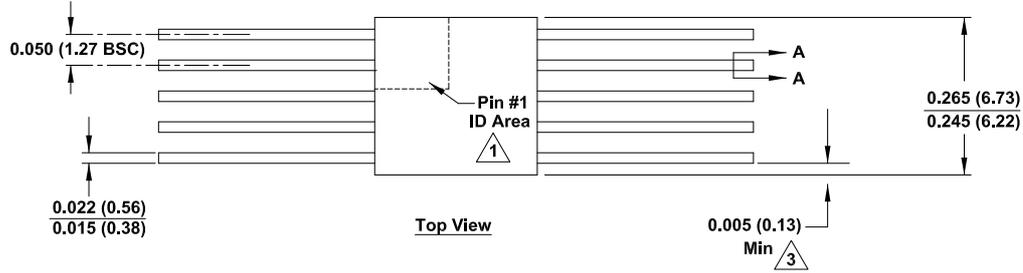


Ceramic Packages for Integrated Circuits

Package Outline Drawing

K10.B
 10 Lead Ceramic Metal Seal Flatpack Package
 Rev 1, 3/2021



Notes:

1. Index area: A notch or a pin one identification mark is located adjacent to pin one and is located within the shaded area shown. The manufacturer's identification is not to be used as a pin one identification mark.
2. The maximum limits of lead dimensions (section A-A) are measured at the centroid of the finished lead surfaces, when solder dip or tin plate lead finish is applied.
3. Measure dimension at all four corners.
4. For bottom-brazed lead packages, no organic or polymeric materials are molded to the bottom of the package to cover the leads.
5. Dimension is measured at the point of exit (beyond the meniscus) of the lead from the body. Dimension minimum is reduced by 0.0015 inch (0.038mm) maximum when solder dip lead finish is applied.
6. The bottom of the package is a solderable metal surface.
7. Dimensioning and tolerancing per ANSI Y14.5M - 1982.
8. Dimensions: INCH (mm), Controlling dimension: INCH.